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Vedi allegato



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PRESS RELEASE

Capital Market Day 2025: Technoprobe presents its strategic roadmap for future growth and confirms its leadership role in the semiconductor testing sector

Cernusco Lombardone (LC), 14 April 2025 – Technoprobe S.p.A., a company listed on *Euronext Milan* and *leader* in the design and production of probe cards (the "**Company**" or "**Technoprobe**") today presents its key growth drivers and strategic roadmap at a dedicated event, with the objective of strengthening its leadership position in the semiconductor testing market.

The increasing complexity driven by rapid technological advancements represents a critical challenge for the industry—one that Technoprobe is well-positioned to address. Backed by its proprietary technological expertise and reinforced by strategic partnerships with **Teradyne** and **Advantest**, the Company is focused on delivering next-generation testing solutions tailored to meet the evolving needs of its customers across both the **front-end** and **back-end** of the semiconductor manufacturing process.

Securing and expanding its leadership in the testing segment remains a top strategic priority. In the **front-end** level, Technoprobe will execute this through the following initiatives:

- **Drive advancements in Logic Semiconductor testing**, with a particular focus on developing specialized solutions for **Advanced Packaging architectures**, whose development has accelerated with the advent of artificial intelligence;
- **Expand the offering of high-speed, high- voltage, radio frequency, and silicon photonics solutions**: the growing volume of data to be processed, along with the increasing speed of interconnections between various types of devices, will continue to drive demand for these products;
- **Broaden its footprint in memory chip testing** by entering the **High Bandwidth Memory (HBM)** segment, a key component in today's artificial intelligence chips.

At the **back-end level**, the synergies created between Technoprobe and DisTech will enable greater penetration into the Device Interface Board segment through the development of a new advanced architecture, **FusionLink**, designed to support the creation of next-generation Printed Circuit Boards (PCBs).

The strategic guidelines outlined are set against a particularly complex geopolitical backdrop, marked by significant instability in global trade policies. In light of this scenario, the Company will present its medium-term target model during the event.

Stefano Felici, CEO of Technoprobe, said: "*The growth journey that Technoprobe has undertaken to date has enabled the Company to achieve a position of leadership—one we are committed to maintaining in the future.*"



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*Our ability to respond promptly to the challenges posed by technological progress is underpinned by the Company's **financial strength**, which ensures we have the resources needed to support **research**, a cornerstone of our continued growth.*

*We are focused on developing increasingly **complex testing solutions** and, leveraging our deep **technological know-how**, on meeting one of the most ambitious challenges in the years ahead: entering one of the **most promising segments in the memory market**.*

*The current economic and political uncertainty demands ongoing attention to **profitability**, which, as of today, is expected to **grow progressively over the medium term**."*

Additional information

Further details will be provided today during the presentation to be held at Villa Gallarati Scotti in Oreno starting at 14:00 CET.

The agenda and live streaming of the event are available on the Technoprobe website at www.technoprobe.com/capital-market-day-2025.

This press release is available on the Technoprobe website www.technoprobe.com in the "Investor Relations" section and on the authorized storage mechanism "eMarket Storage" (www.emarketstorage.it).

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Technoprobe Group

Technoprobe is a leading semiconductor and microelectronics company. Established in 1996, Technoprobe specializes in the design and manufacture of electro-mechanical interfaces called Probe Cards for chip function testing. Probe Cards are high-tech devices – tailored to the specific chip – that allow you to test the operation of chips during their construction process. These are projects and technological solutions that guarantee the operation and reliability of devices that play a decisive role in the Information Technology, 5G, Internet of Things, home automation, automotive, and aerospace industries. Technoprobe has its headquarters in Italy, in Cernusco Lombardone (LC). Since May 2, 2023, Technoprobe has been listed on the Euronext Milan market. For more information: www.technoprobe.com

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